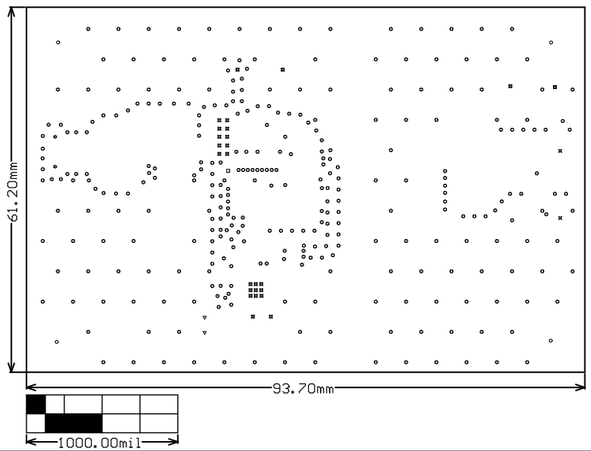
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer	CF-005	2.76mil		
	Dielectric 1	FR-4 High Tg	8.00mil	4.1	
2	Signal Layer 1	CF-004	1.40mil		
	Dielectric1	FR-4 High Tg	36.00mil	4.8	
3	Signal Layer 2	CF-004	1.40mil		
	Dielectric 2	FR-4 High Tg	8.00mil	4.1	
4	Bottom Layer	CF-005	2.76mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Total board thickness: 61.11mil

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	21	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
✪	314	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
◘	4	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
✡	2	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
□	1	52.00mil (1.321mm)	PTH	Round	Top Layer - Bottom Layer	
⌘	2	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	350 Total					



DESIGN INFORMATION

MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 7.874 MIL
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: LM5185EVM-SIO
DESIGNED FOR: Public Release
FILE NAME: BSR268A.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BSR268	REV: A	SVN REV: Not in version control
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 7/13/2023 3:17:01 PM	TEXAS INSTRUMENTS	

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ENGINEER: Y Xi	LAYOUT BY: K Nielson
SCALE: 1.00	ALTIUM DESIGNER VERSION: 23.5.1.21